

ABSTRACT OF THE DISCLOSURE

A method of making a compliant microelectronic package includes providing a first substrate having a top surface with conductive pads and an opening extending therethrough to the first substrate so that a bottom surface of the second substrate confronts a top surface of the first substrate. A microelectronic element is attached to the first substrate so that a back face of the microelectronic element confronts the top surface of the first substrate. The contacts of the microelectronic element are electrically interconnected with the conductive pads of the second substrate. A dielectric sheet having conductive leads is juxtaposed with the first substrate. The second ends of the leads are electrically interconnected with the conductive pads of the second substrate, and the dielectric sheet and the second substrate are moved away from one another so as to vertically extend the leads.

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